

Now Available!

THE WORLDWIDE IC PACKAGING MARKET

2013 EDITION

**The Most Comprehensive Report Available
On The Global IC Packaging Industry**

Report Highlights

- **Industry Overview**
 - ◆ Economic Overview
 - ◆ Semiconductor Industry Analysis

- **Worldwide IC Packaging Market Forecasts, 2011–2017**
 - ◆ Units
 - ◆ Package Prices
 - ◆ Packaging Revenue
 - ◆ By Semiconductor Product
 - ◆ By Package Family
 - ◆ By I/O Range

- **OSAT IC Packaging Market Forecasts, 2011–2017**
 - ◆ Units
 - ◆ Package Prices
 - ◆ Packaging Revenue
 - ◆ Competitive Rankings
 - ◆ Company Profiles

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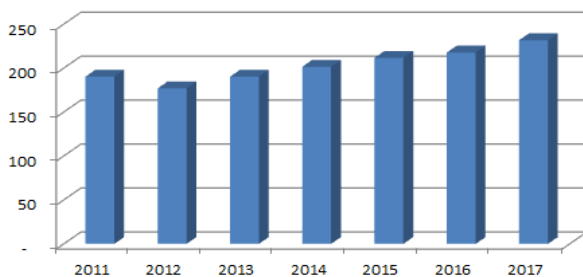
Synopsis

While the integrated circuit (IC) market tends to be cyclical in nature, the general trend is for more ICs to be integrated into more products over time. While military was once the main driver of electronics, currently the market is being driven by demand for handheld consumer devices and the adjoining infrastructure. The automobile industry is also gaining steam, and vehicles are laden with semiconductor devices.

A year of unprecedented growth in 2010 (IC revenue grew 40.6% while units expanded 35.5%) followed the worst economic downturn since the great depression. The year 2012 saw a softening in the market, which is typical of U.S. Presidential election years. A steady climb is anticipated in the market for 2013 and beyond, although economic uncertainty in Europe and developments in unrest in the Middle East could hamper growth.

New Venture Research (NVR), in the **2013 Edition of The Worldwide IC Packaging Market**, analyzes the semiconductor industry and uses this analysis to forecast the future of the global IC packaging market. The report begins with an economic and industry overview, and historic and future unit and revenue graphs.

IC Unit Shipments (B)



Following this high-level review, the report presents forecasts for each semiconductor product type, and segments these products by package family and I/O count range. Packaging revenue figures are displayed for each segment, based on prices charged in the outsourced assembly and test (OSAT) market. The package families are then rolled up by I/O count and semiconductor product. In doing so, the report generates the total value of the IC packaging industry.

Next, the report presents NVR's continuing, extensive coverage of the OSAT market. OSATs will continue to assume a larger share of the world's IC packaging business. The report breaks the OSAT market down by package families and major product categories providing units and revenue for each category. To help you further assess this group of companies, the report profiles the activities of the world's largest OSAT companies and the packages they offer.

The Worldwide IC Packaging Market, 2013 Edition continues NVR's leadership position in assessing the status and future of IC packaging. This report is an effective and economical tool for any company associated in the semiconductor industry to aid in assessing their own markets and potential areas of growth. The report sells for \$3495 and is delivered by email as a single-user PDF file. Extra single-user licenses sell for \$250 each and a corporate license is \$1000. With the purchase of the report, an Excel spreadsheet of all tables may be obtained for an additional \$750 and a printed copy for \$250.

About the Author

Sandra L Winkler has been an industry analyst beginning in 1988, and since 1995, a staff member of Electronic Trend Publications, currently New Venture Research. She has produced numerous off-the-shelf and custom reports. Ms. Winkler began her analyst career in the telecommunications industry, with Frost and Sullivan. Since 1995, she has focused on the semiconductor packaging industry, and has authored more than 30 widely cited reports on the topic, including *The Worldwide IC Packaging Market*, *Advanced IC Packaging Markets and Trends*, and *IC Packaging Materials*. She also writes for *Chip Scale Review* magazine, *Global SMT & Packaging News*, and contributes to the IEEE/CPMT newsletter and other media. Ms. Winkler has an MBA from Santa Clara University. She is on the executive planning committee of the IEEE/CPMT Santa Clara Valley chapter, and serves as Luncheon Program Chair.

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Economic Overview

Industry Overview

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Device Types: Package Types: I/O Count:

MPU	DIP	004-018
MCU	SOT	020-032
DSP	SO	034-100
DRAM	TSOP	104-304
Flash	DFN	308-999
SRAM	CC	1,000 +
ROM/EPROM	QFP	
EEPROM/Other	QFN	
Digital Bipolar	PGA	
Standard Logic	BGA	
Gate Arrays	FBGA	
Standard Cell/PLD	WLP	
Display Drivers	DCA	

Special Purpose Logic and Analog - All Segments

Chapter 5:

IC Package Forecast by Package Family

	<u>I/O Count Range</u>
DIP	
SOT	004-018
SO	020-032
TSOP	034-100
DFN	104-304
CC	308-999
QFP	1,000+
QFN	
PGA	
BGA	
FBGA	
WLP	
DCA	

Chapter 6: Packaging OSAT Market

Market Overview

Contractor Rankings

Unit, Revenue, Pricing Forecasts by Package Family

DIP
SOT
SO
TSOP
DFN
CC
QFP
QFN
PGA
BGA
FBGA
WLP

OSAT Ranking

Chapter 7: Company Profiles

Amkor	Millennium Microtech
Anst China	NANIUM
ASE	Nantong Fujitsu
Azimuth	OSE
Carsem	Powertech
ChipMOS	Shinko Electric
Cirtek	Signetics
CORWIL Technology	Sigurd
Deca Technologies	Siliconware
FlipChip Int'l	SPEL
Hana Microelectronics	STATS ChipPAC
Hana Micron	Teramikros
I2A	Tianshui Huatian Tech
J-Devices	Unisem
Jiangsu Changjiang	UTAC
Lingsen Precision	Vigilant Technology
	XinTec

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 ROM and EPROM
 EEPROM/Other Memory
 Digital Bipolar
 Standard Logic
 Gate Arrays
 Cell-Based and PLD
 Display Drivers
 Custom Logic
 Amplifiers
 Interfaces
 Voltage Regulators
 Data Converters
 Custom Analog

DIP Forecasts—3 I/O Ranges
SOT Forecasts
SO Forecasts—3 I/O Ranges
TSOP Forecasts—3 I/O Ranges
DFN Forecasts—2 I/O Ranges
CC Forecasts—2 I/O Ranges
QFP Forecasts—2 I/O Ranges
QFN Forecasts—4 I/O Ranges
PGA Forecasts—2 I/O Ranges
BGA Forecasts—4 I/O Ranges
FBGA Forecasts—6 I/O Ranges
WLP Forecasts—4 I/O Ranges
DCA Forecasts—5 I/O Ranges
Total IC Packaging Revenue

OSAT Total Forecast
OSAT DIP Forecast
OSAT SOT Forecast
OSAT SO Forecast
OSAT TSOP Forecast
OSAT DFN Forecast
OSAT CC Forecast
OSAT QFP Forecast
OSAT QFN Forecast
OSAT PGA Forecast
OSAT BGA Forecast
OSAT FBGA Forecast
OSAT WLP Forecast
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